

ABSTRACT

[0044] The invention provides a method and apparatus for temporarily isolating a die from other dice on a wafer commonly connected to one or more common conductors. The conductors are connected to each die through a temporary isolation device, such as a diode. The common conductor supplies a signal to all dice during one set of test procedures, while the temporary isolation device can be used to isolate a die from the common conductor during another set of test procedures.

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